## Special Topics on Basic EECS I VLSI Devices Lecture 19 - Memory

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## L19 is for memory devices.

- L18 was for the MOS capacitor.
- Due to my business trip (International Memory Workshop),
  - -L19 was recorded.

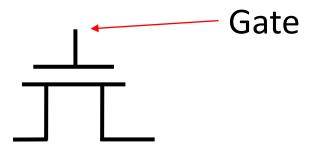




L20 (May 20) will consider the MOS capacitor, again.

#### Note that

- To understand this lecture, we must first understand the operation of MOS transistors.
  - However, we are still considering the MOS capacitor... ☺
  - Treat the MOS transistor as a switch controlled by the gate voltage.
  - Its threshold voltage is  $V_t$ .

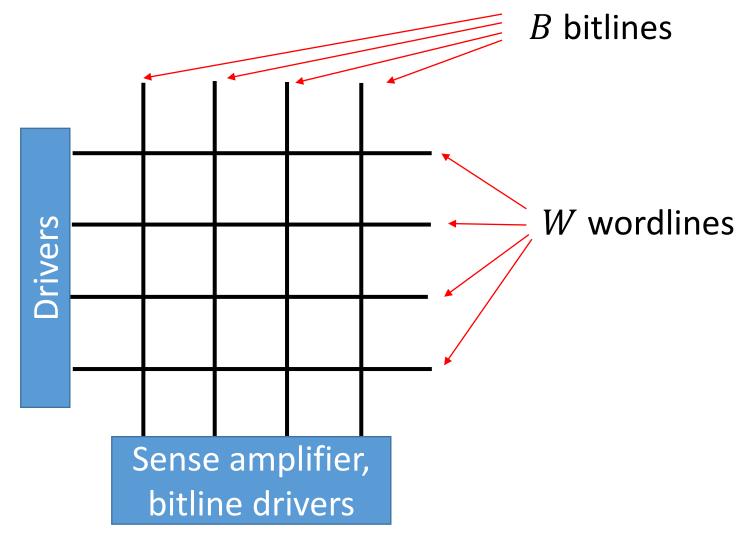


## Memory devices

- Three representative memory devices
  - -SRAM
  - -DRAM
  - -NAND
- There are also "new" memory devices.
  - FeRAM
  - PCRAM
  - -STT-MRAM
  - -ReRAM

## **Array of memory cells**

•  $W \times B$  bits



## **SRAM (Static Random-Access Memory)**

For the SRAM device, watch my previous lecture.

-Title: [DIC2023] L25\_20231205

-Starting point: 35:05

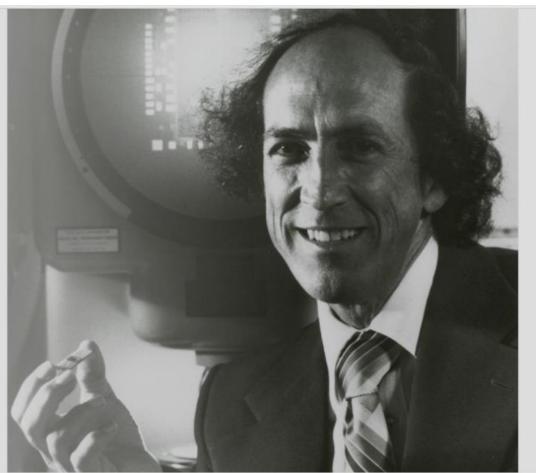


## **DRAM (Dynamic Random-Access Memory)**

 Robert Dennard, the inventor of DRAM, passed away on April 23, 2024.

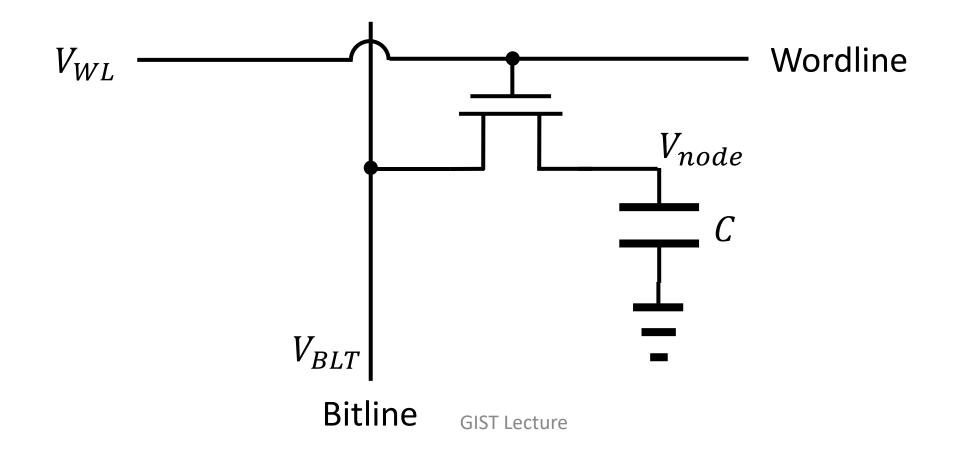
#### Robert Dennard

The inventor of DRAM laid the foundation for modern computing and received the US National Medal of Technology



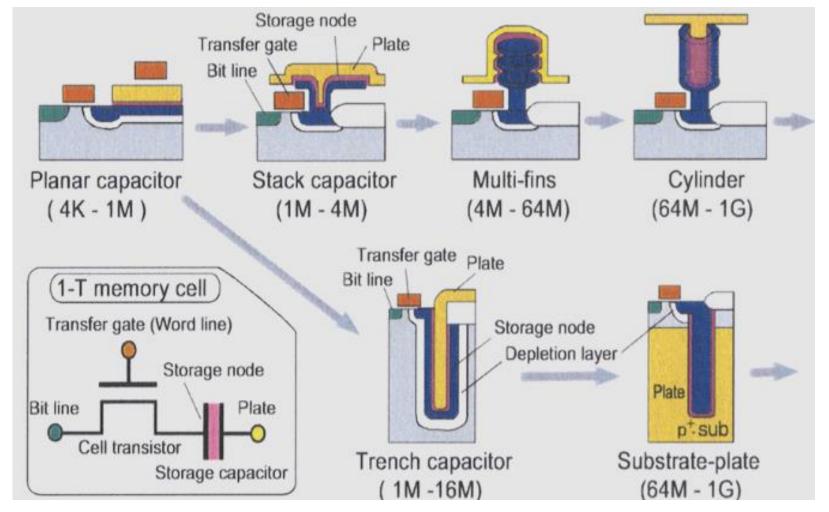
#### **1T1R**

- It is considerably smaller in silicon area than a CMOS SRAM cell.
  - -The cell is in state "1" when there is charge in the capacitor.



### Capacitor

Its capacitance is ~ 10 fF nowadays.



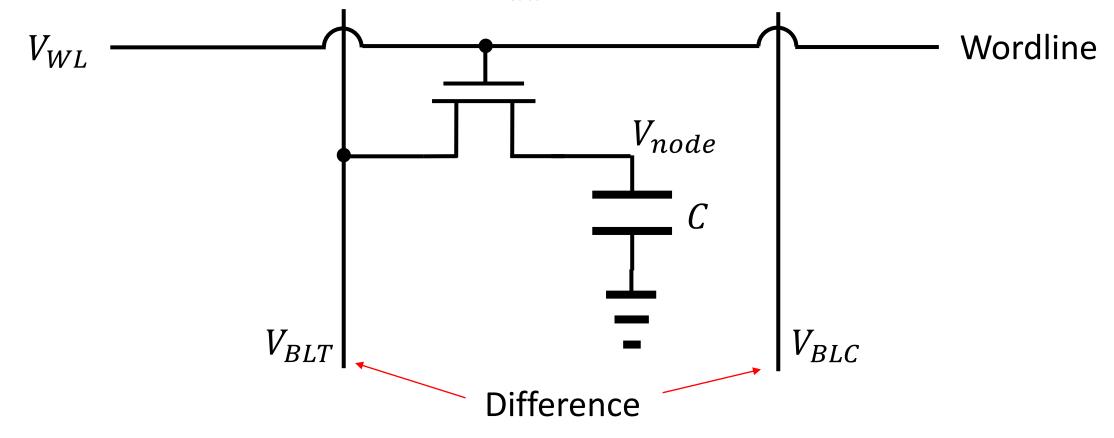
Major advancement in DRAM cell innovation (H. Sunami, ICSICT 2008)

## **WRITE** operation

- It is straightforward to write a "0" to a DRAM cell.
  - $-V_{WL}$  is  $V_{dd}$ .  $V_{BLT}$  is 0 V.
  - -Then,  $V_{node}$  is 0 V.
- In writing a "1,"
  - $-V_{WL}$  is boosted to be higher than  $V_{dd} + V_t$ .  $V_{BLT}$  is  $V_{dd}$ .
  - -Then,  $V_{node}$  can reach  $V_{dd}$ .
- After the storage node is fully charged or discharged,
  - The wordline is brought back to its standby voltage. (The transistor is turned off.)

## **READ** operation

- A cross-coupled CMOS sense amplifier
  - -BLT and BLC are precharged to  $V_{dd}/2$ .



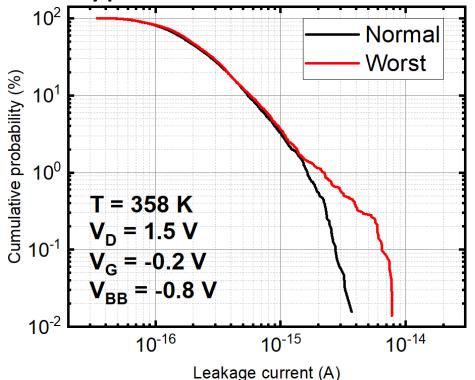
## Sense amplifier

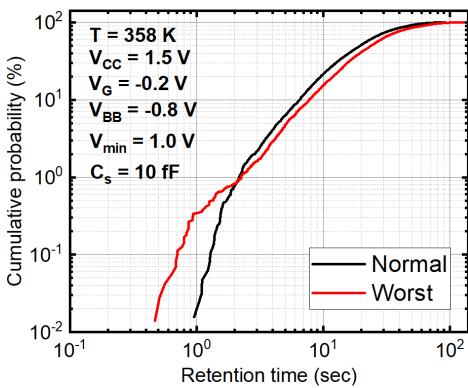
- The same boost of the wordline to  $V_{WL} > V_{dd} + V_t$  is applied.
  - If a "0" bis it stored in the cell,  $V_{BLT}$  is discharged to below  $V_{dd}/2$ .
  - If a "1" bit is stored in the cell,  $V_{BLT}$  is charged to above  $V_{dd}/2$ .
- ullet After a differential signal is developed between BLT and BLC,
  - -The sense amplifiers is activated.
  - It restores  $V_{node}$ . (Refresh)
- Read signal,  $V_s$

$$V_s(C_{cell} + C_{bitline}) = \left(V_{node} - \frac{V_{dd}}{2}\right)C_{cell}$$
 Taur, Eq. (9.11)

## Leakage current

- The charge stored in the capacitor leaks away over time.
  - Periodic read and refresh are necessary.
  - Retention time: Time interval between data refreshes
  - A typical worst-case data retention time is about 100 ms.





# Thank you!